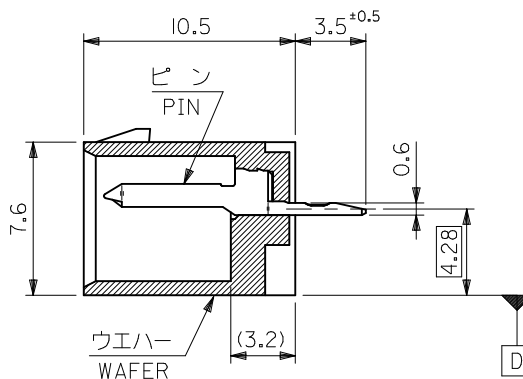
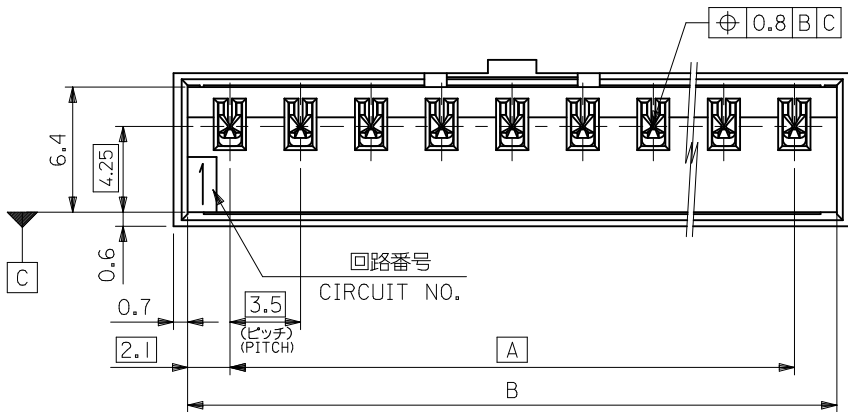


基板取付穴推奨寸法 (参考) (t=1.6)  
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)



注記  
NOTES

1. 嵌合相手 : 51067 シリーズ  
MATE WITH : 51067 SERIES
2. 材質  
MATERIAL  
ウエハー : PBTP (ガラス15%入り)、UL94V-0  
WAFER : PBTP (G.F 15%), UL94V-0  
ピン : 53258-\*\*10 [リン青銅、銅下地、半田メッキ (t=0.254)]  
PIN : [PHOS. BRO., TIN-LEAD(9:1) OVER COPPER PLATING (t=0.254)]  
53258-\*\*20 [黄銅、銅下地、半田メッキ (t=0.254)]  
[BRASS, TIN-LEAD(9:1) OVER COPPER PLATING (t=0.254)]

6.1	9.1	7.7	3.5	53258-0220	2
(D)	C	B	A	ENG. NO.	CKT. 種数

REVISED EC NO: J2012-0723 DRAWN: SATO 2011/11/24 CHKD: KASAKAWA 2011/11/24 APPR: YOITO 2011/11/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY K. ASAKAWA	DATE '89/10/13	TITLE 3.5 W/B CONN WAFER ASSY (ST)				
		10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRAMOTO	DATE '93/6/29					
		30 OVER	±0.3	APPROVED BY YOITO	DATE 2011/11/28					
		ANGULAR ±3 °		MATERIAL NO. SEE CHART		MATERIAL NO. MOLEX INCORPORATED		DOCUMENT NO. SD-53258-012		SHEET NO. 1 OF 1
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				